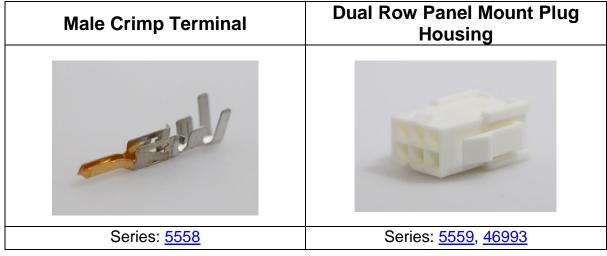


MINI-FIT JR. **WIRE TO WIRE & WIRE TO BOARD CONNECTOR SYSTEM**



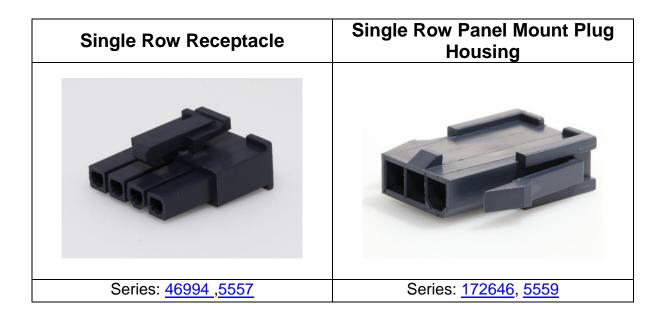


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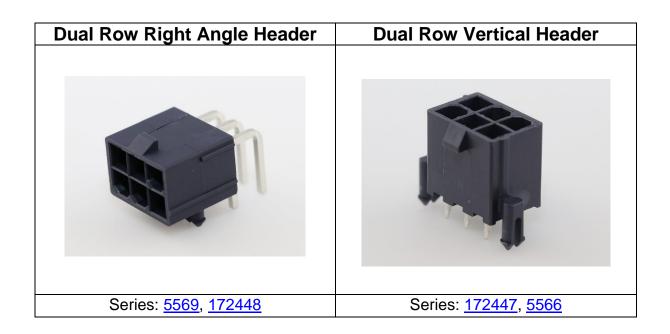


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1.0 SCOPE

This Product Specification covers performance requirements for the MINI-FIT JR. 4.20 mm (.165 inch) centerline (pitch) wire to board and wire to wire connector system terminated with 16 to 28 AWG standard, copper wire using Crimp technology with Tin or 30µ" Gold plating.

2.0 PRODUCT DESCRIPTION

2.1 PRODUCT NAME AND SERIES NUMBER (S)*

	Table 1 – WIRE-TO-WIRE											
Description Series UL CSA IEC Primary Product Number (600V) (600V) (250V) Specification												
Female Crimp Terminal	<u>5556</u>	n/a	n/a	Yes	<u>PS-5556-001</u>							
Receptacle Housing	<u>5557</u>	Yes	Yes	Yes	PS-5556-001							
Male Crimp Terminal	<u>5558</u>	n/a	n/a	Yes	PS-5556-001							
Plug Housing	<u>5559</u>	Yes	Yes	Yes	PS-5556-001							
Plug Housing	<u>45776</u>	Yes	Yes	Yes	PS-5556-001							
Receptacle Housing	<u>46992</u> / <u>46994</u>	Yes	Yes	Yes	PS-5556-001							
Plug housing	46993 / 172646	Yes	Yes	Yes	PS-5556-001							

Table 2 – WIRE-TO-BOARD										
Description	Series Number	UL (600V)	CSA (600V)	IEC (250V)	Primary Product Specification					
Female Crimp Terminal	<u>5556</u>	n/a	n/a	Yes	PS-5556-001					
Receptacle Housing	<u>5557</u>	Yes	Yes	Yes	PS-5556-001					
Vertical Header	<u>5566</u>	Yes	Yes	Yes	PS-5556-001					
Right Angle Header	<u>5569</u>	Yes	Yes	Yes	PS-5556-001					
Receptacle Housing	<u>46992</u> / <u>46994</u>	Yes	Yes	Yes	PS-5556-001					
Vertical Header	<u>172447</u> / <u>172647</u>	Yes	Yes	Yes	PS-5556-001					
Right Angle Header	<u>172448</u> / <u>172648</u>	Yes	Yes	Yes	PS-5556-001					

^{*}Other products conforming to this specification are noted on the individual drawing

2.2 DIMENSIONS, MATERIALS, PLATING AND MARKINGS

Dimensions & Plating: See individual sales drawings

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2.3 ENVIRONMENTAL CONFORMANCE

To find product compliance information:

- a. Go to molex.com
- b. Enter the part number in the search field.
- c. At the bottom of the page go to "Environmental" to see compliance status.

2.4 SAFETY AGENCY APPROVALS

UL File: E29179

CSA Certificate: LR 19980 IEC 61984 Certification:



Tested to and found in compliance with IEC 61984. NRTL type examination certificate available upon request. Contact Molex Safety team for questions regarding certification on specific part numbers.

Note: Safety agency approval is granted for the connector assembled with its associated terminals. The approval is documented in the agency file/license by the series number of the housing only. The terminal series number will not appear in the agency file/license as a stand-alone approved product. As a result, only the housings may bear the agency certification mark. Please note that even though the housings are marked as approved product, the safety agency approval does not apply if any terminals are installed other than those established for use with the product.

3.0 APPLICABLE DOCUMENTS AND SPECIFICATIONS

3.1 MOLEX DOCUMENTS

See series specific sales drawings and the other sections of this specifications for the necessary referenced documents and specifications. For Application Tooling refer to the specific terminal part number page in Molex Website.

Mini-Fit Jr. Test Summary TS-5556-002-001

Mini-Fit Jr. Dual Wire Termination Test Summary 55560010-TS

Mini-Fit Jr. Appearance Specification AS-5557-001

Molex Quality Crimping Handbook Order No. 63800-0029

Molex Solderability Specification SMES-152

Molex Heat Resistance Specification AS-40000-5013

Molex Moisture Technical Advisory AS-45499-001

Molex Package Handling Specification 454990100-PK

ATS - Application Tooling Specification*

*Application Tooling Specification for terminals is not provided in this document. ATS for terminals available from respective terminal part number page in Molex.com

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3.2 INDUSTRY DOCUMENTS

EIA-364-1000.01 UL 1977 CSA C22.2 No. 182.3-M1987 IEC 61984

4.0 ELECTRICAL PERFORMANCE RATINGS

4.1 VOLTAGE*

600 Volts AC (RMS) or 600 Volts DC max.

* Voltage rating based on UL 1977. Maximum voltage allowed may vary dependent upon "End Use Application". Refer to the applicable end use standard for additional information on Voltage, Creepage and Clearance requirements.

4.2 APPLICABLE WIRES

	Applicable Wire Gauges	Maximum Insulation Diameter
Single Wire Termination	Stranded Copper 16 AWG	3.15 mm / 0.124 Inches
onigle wire remination	Stranded Copper 18-24 AWG	3.10 mm / 0.122 Inches
	Stranded Copper 22-28 AWG	1.80 mm / 0.071 Inches
Dual Wire Termination	Stranded Copper 18-22 AWG ¹	1.75 mm / 0.069 Inches per wire 3.4 mm / 0.134 Inches cumulative

4.2.1 APPLICABLE TERMINALS FOR DUAL WIRE TERMINATION¹

Terminal Crimp Size Single Wire	Dual Wire Termination Wire Gauges
16 AWG	18 AWG with 22 AWG 20 AWG with 22 AWG 20 AWG with 20 AWG
18-24 AWG	22 AWG with 22 AWG

¹ See specific terminal ATS on Molex.com for allowable dual-wire configurations.

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4.3 MAXIMUM CURRENT RATING**

	Table 3 – MAXIMUM CURRENT RATING (Amperes) Wire-to-Wire and Wire-to-Board										
		Brass				Phosp	hor Bron	ze			
Ckt.Size Wire ²	2 & 3	4 - 6	7 - 10	12 - 24	Ckt.Size Wire ²	2 & 3	4 - 6	7 - 10	12 - 24		
AWG#16	9	8	7	6	AWG#16	8	7	6	5		
AWG#18	9	8	7	6	AWG#18	8	7	6	5		
AWG#20	7	6	5	5	AWG#20	6	5	4	4		
AWG#22	5	4	4	4	AWG#22	4	3	3	3		
AWG#24	4	3	3	3	AWG#24	3	2	2	2		
AWG#26	3	2	2	2	AWG#26	2	1	1	1		
AWG#28	2	1	1	1	AWG#28	1	1	1	1		

Note: PCB trace design may greatly affect temperature rise results in Wire-to-Board Applications.

**Current rating is application dependent and may be affected by the wire rating such as listed in UL-60950-1. Each application should be evaluated by the end user for compliance to specific safety agency requirements. The ratings listed in the chart above are per Molex test method based on a 30°C maximum temperature rise over ambient temperature and are provided as a guideline. Appropriate de-rating is required based on circuit size, ambient temperature, copper trace size on the PCB, gross heating from adjacent modules/components and other factors that influence connector performance. Wire size, insulation thickness, stranding, tin coated or bare copper, wire length & crimp quality are other factors that influence current rating.

² Current rating for dual-wire termination dictated by the largest single wire terminated in connection.

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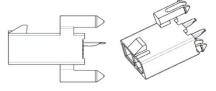


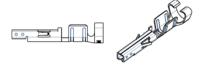
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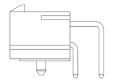


4.4 TEMPERATURE

		Terminal Type						
	Formed - Brass	Solid - Brass	Phos Bronze					
Operating: *	-40°C to +80°C	-40°C to +105°C	-40°C to +105°C					
Nonoperating:	-40°C to +80°C	-40°C to +105°C	-40°C to +105°C					









Example header with "formed" terminals

Example "formed" crimp terminals

Example header with "solid" terminals

Field Temperature and Field Life: 65° C for 3 years

Note: Temperature life test (section 6.3, 7.3 item 2) and ratings are based on the assumption that the contact spends its entire field life at the rated maximum field temperature (based on EIA-364-1000, table 8)

*Temperature values include 30°C terminal temperature rise at maximum rated current

4.5 DURABILITY

Tin plated: 30 mating cycles Gold plated: 30 mating cycles

4.6 GLOW WIRE

The following series are glow wire capable: 46992, 46993, 46994, 172646, 172447, 172448, 172648, 45776, 5566. Representative samples were tested and found compliant with EN 60695-2-11-2001 / IEC 60695-2-11-2000 Glow Wire Test Methods for End-Products. These were additionally investigated for compliance with EN 60335-1 / IEC 60335-1 750C / 2 sec with no flaming. VDE Test report available upon request.

5.0 QUALIFICATION

Laboratory conditions and sample selection are in accordance with EIA-364-1000.

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6.0 PERFORMANCE - WIRE TO WIRE CONNECTION

6.1 **ELECTRICAL PERFORMANCE**

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
6.1.1	Initial Contact Resistance (Low Level)	Mate connectors: apply a maximum voltage of 20 mV and a current of 100 mA Wire resistance and traces shall be removed from the measured value.	10 milliohms MAXIMUM [initial]
6.1.2	Insulation Resistance	Mate connectors: apply a voltage of 500 VDC between adjacent terminals and between terminals to ground.	1000 Megohms MINIMUM
6.1.3	Dielectric Withstanding Voltage	Mate connectors: apply a voltage of 2200 VAC for 1 minute between adjacent terminals and between terminals to ground.	No breakdown. Current leakage < 5 mA
6.1.4	Temperature Rise (via Current Cycling)	Mate Connectors. Measure the temperature rise at the rated current after 96 Hours, during current cycling (45 Minutes ON and 15 minutes OFF per Hour) for 240 Hours, and after final 96-hour steady state.	Temperature rise: +30°C MAXIMUM

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6.2 **MECHANICAL PERFORMANCE**

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
6.2.1	Terminal Mate and Unmate Forces Per Circuit	Insert and withdraw terminal (male to female) at a rate of 25 ± 6 mm (1 ± 1/4 inch) per minute with latch disabled.	14.7 N (3.30 lbf) MAXIMUM insertion force and 0.5 N (0.11 lbf) MINIMUM withdrawal force
6.2.2	Crimp Terminal Retention Force (in Housing)	Axial pullout force on the terminal in the housing at a rate of 25 ± 6 mm (1 ± ¼ inch) per minute.	30 N (6.74 lbf) MINIMUM retention force
6.2.3	Durability	Mate connectors up to 30 cycles at a maximum rate of 10 cycles per minute Based on mated pairs of 30μ" Au or 100μ" tin at the contact interface.	20 milliohms maximum (change from initial)
6.2.4	Vibration (Random)	Mate connectors and vibrate per EIA 364-28, test condition VII, letter D. Test Duration: 15 minutes in each axis.	20 milliohms MAXIMUM (change from initial) and Discontinuity < 1 microsecond
6.2.5	Shock (Mechanical)	Mate connectors and shock at 50 g's with ½ sine wave (11 milliseconds) shocks in the ±X, ±Y, ±Z axes, (18 shocks total).	20 milliohms MAXIMUM (change from initial) and Discontinuity < 1 microsecond
6.2.6	Wire Pullout Force (Axial)	Apply an axial pullout force on the wire at a rate of 25 ± 6 mm (1 ± ¼ inch) per minute without influence from the insulation crimp. Wire pullout force is applicator dependent. Refer to relevant Molex Applicator Tooling specification.	16 Awg = 68.4 N (15.4 lbf) Min. 18 Awg = 88.0 N (19.8 lbf) Min. 20 Awg = 58.7 N (13.2 lbf) Min. 22 Awg = 39.1 N (8.8 lbf) Min. 24 Awg = 29.3 N (6.6 lbf) Min. 26 Awg = 19.6 N (4.4 lbf) Min. 28 Awg = 9.8 N (2.2 lbf) Min.

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6.2 **MECHANICAL PERFORMANCE CONTINUED**

ITEM	DESCRIPTION	TEST CONDITION		REQUIREMENT
6.2.7	Crimp Terminal Insertion Force (into Housing)	Apply an axial insertion force on the terminal at a rate of 25 ± 6 mm (1 ± ¼ inch) per minute.	М	15.0 N (3.37 lbf) AXIMUM insertion force
6.2.8	Normal	Apply a perpendicular force to	Sn	1.47 N (150 grams) MINIMUM
0.2.0	Force	contacts.	Au	0.49 N (50 grams) MINIMUM
6.2.9	Panel Insertion and Withdrawal Forces (5559, 46993, 172646 Series)	Insert and withdraw a connector at a rate of 25 ± 6 mm (1 ± ¼ inch) per minute. Applies only to plugs with panel retention features.	Du Sin	225 N (50.7 lbf) AXIMUM insertion force and ual Row: 157 N (35.3 lbf) gle Row: 133 N (29.9 lbf) NIMUM withdrawal force
6.2.10	Panel Insertion and Withdrawal Forces (45776 Series)	Insert and withdraw a connector at a rate of 25 ± 6 mm (1 ± ¼ inch) per minute.		225 N (50.7 lbf) AXIMUM insertion force and 3 N (29.9 lbf) MINIMUM withdrawal force
6.2.11	Thumb latch Operation Force	Depress latch at a speed rate of 25 ± 6 mm (1 $\pm \frac{1}{4}$ inch) per minute.	22	.2 N (5.0 lbf) MAXIMUM
6.2.12	Thumb latch Yield Strength	Mate loaded connectors fully. Pull connectors apart at a speed rate of 25 ± 6 mm (1 ± ¼ inch) per minute. (after 1st mate)		68 N (15.3 lbf) MINIMUM

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6.3 **ENVIRONMENTAL PERFORMANCE**

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
6.3.1	Thermal Shock	Mate Connectors: Expose for 5 Cycles between temperatures -55 °C and 105 °C; Dwell 0.5 Hours at each temperature.	20 milliohms MAXIMUM (change from initial) Visual: No Damage Dielectric Strength per 6.1.3 except 1500VAC test voltage Insulation Resistance per 6.1.2
6.3.2	Thermal Aging	Mate connectors; expose to: 96 hours at 105 ± 2°C	20 milliohms MAXIMUM (change from initial) and Visual: No Damage
6.3.3	Humidity (Steady State)	Mate connectors: expose to a temperature of 60 ± 2°C with a relative humidity of 90-95% for 96 hours. Remove surface moisture and air dry for 1 hour prior to measurements.	20 milliohms MAXIMUM Visual: No Damage Dielectric Strength per 6.1.3 except 1500VAC test voltage Insulation Resistance per 6.1.2
6.3.4	Cold Resistance	Mate connectors: Duration: 96 hours; Temperature: -40 ± 3°C	20 milliohms MAXIMUM (change from initial) and Visual: No Damage
6.3.5	Mixed Flowing Gas	EIA-364-65 with Class IIa Gas concentrations 10 days mated (30µ" Gold plated only)	20 milliohms MAXIMUM (change from initial) and Visual: No Damage
6.3.6	Cyclic Temperature and Humidity	Mate connectors: expose to 24 cycles from 25 °C / 80% RH to 65 °C / 50% RH ramp time: 0.5hr dwell time: 1hr Per EIA-364-1000	20 milliohms MAXIMUM (change from initial) and Visual: No Damage

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7.0 **PERFORMANCE - WIRE TO BOARD CONNECTION**

7.1 **ELECTRICAL REQUIREMENTS**

ITEM	DESCRIPTION	TEST CONDITION	REQURIEMENT
7.1.1	Contact Resistance (Low Level)	Mate connectors: apply a maximum voltage of 20 mV and a current of 100 mA. Wire resistance shall be removed from the measured value.	10 milliohms MAXIMUM [initial]
7.1.2	Insulation Resistance	Mate connectors: apply a voltage of 500 VDC between adjacent terminals and between terminals to ground.	1000 Megohms MINIMUM
7.1.3	Dielectric Withstanding Voltage	Mate connectors: apply a voltage of 2200 VAC for 1 minute between adjacent terminals and between terminals to ground.	No breakdown. Current leakage < 5 mA
7.1.4	Temperature Rise (via Current Cycling)	Mate connectors. Measure the temperature rise at the rated current after 96 hours, during current cycling (45 minutes ON and 15 minutes OFF per hour) for 240 hours, and after final 96-hour steady state.	Temperature rise: +30°C MAXIMUM

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7.2 **MECHANICAL REQUIREMENTS**

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
7.2.1	Terminal Mate and Unmate Forces Per Circuit	Insert and withdraw terminal (male to female) at a rate of 25 ± 6 mm (1 ± 1/4 inch) per minute with latch disabled.	14.7 N (3.30 lbf) MAXIMUM insertion force and 0.5 N (0.11 lbf) MINIMUM withdrawal force
7.2.2	Crimp Terminal Retention Force (in Housing)	Axial pullout force on the terminal in the housing at a rate of 25 ± 6 mm (1 ± 1/4 inch) per minute.	30 N (6.74 lbf) MINIMUM retention force
7.2.3	Durability	Mate connectors up to 30 cycles at a maximum rate of 10 cycles per minute Based on mated pairs of 30µ" Au or 50µ" tin at the contact interface	20 milliohms maximum (change from initial)
7.2.4	Vibration (Random)	Mate connectors and vibrate per EIA 364-28, test condition VII, letter D. Test Duration: 15 minutes in each axis.	20 milliohms MAXIMUM (change from initial) and Discontinuity < 1 microsecond
7.2.5	Shock (Mechanical)	Mate connectors and shock at 50 g's with ½ sine wave (11 milliseconds) shocks in the ±X, ±Y, ±Z axes, (18 shocks total).	20 milliohms MAXIMUM (change from initial) and Discontinuity < 1 microsecond
7.2.6	Wire Pullout Force (Axial)	Apply an axial pullout force on the wire at a rate of 25 ± 6 mm (1 ± ¼ inch) per minute without influence from the insulation crimp. Wire pullout force is applicator dependent. Refer to relevant Molex Application Tooling specification.	16 Awg = 68.4 N (15.4 lbf) Min. 18 Awg = 88.0 N (19.8 lbf) Min. 20 Awg = 58.7 N (13.2 lbf) Min. 22 Awg = 39.1 N (8.8 lbf) Min. 24 Awg = 29.3 N (6.6 lbf) Min. 26 Awg = 19.6 N (4.4 lbf) Min. 28 Awg = 9.8 N (2.2 lbf) Min.
7.2.7	Crimp Terminal Insertion Force (into Housing)	Apply an axial insertion force on the terminal at a rate of 25 ± 6 mm (1 ± 1/4 inch) per minute.	15.0 N (3.37 lbf) MAXIMUM insertion force

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7.2 **MECHANICAL PERFORMANCE CONTINUED**

ITEM	DESCRIPTION	TEST CONDITION		REQUIREMENT	
7.2.8	Normal	Apply a perpendicular force to	Sn	1.47 N (150 grams) MINIMUM	
7.2.0	Force	contacts.	Au	0.49 N (50 grams) MINIMUM	
7.2.9	Solid PC Tail Header Pin Retention Force (in housing) (5569, 172448, 172648 Series)	Apply axial push force on the terminal in the housing at a rate of 25 ± 6mm (1 ± 1/4 inch) per minute.		9.81 N (2.20 lbf) MINIMUM RETENTION FORCE	
7.2.10	Stamped PC Tail Terminal Retention Force (in housing) (5566, 172447, 172647 Series)	Apply axial push force on the terminal in the housing at a rate of 25 ± 6mm (1 ± 1/4 inch) per minute.		9.81 N (2.20 lbf) MINIMUM RETENTION FORCE	
7.2.11	Thumb latch Operation Force	Depress latch at a speed rate of 25 ± 6 mm (1 ± ¼ inch) per minute.	22.2	22.2 N (5.0 lbf) MAXIMUM	
7.2.12	Thumb latch Yield Strength	Mate loaded connectors fully. Pull connectors apart at a speed rate of 25 ± 6 mm (1 ± ¼ inch) per minute. (after 1st mate)	1 88	68 N (15.3 lbf) MINIMUM	
7.2.13	PCB Engagement Forces	Engage a connector at a rate of 25 ± 6 mm (1 ± ¼ inch) per minute. Applies to parts with PCB retention features only with PCB holes at nominal diameter and location. Values will vary with PCB material, PCB fabrication, and pag type. 26.7 to (6.0 to 1) For 5566, 172 4.4 to 4 (1.0 TO		5569, 172448, 172648: 26.7 to 66.7 N (6.0 to 15.0 lbf) 5566, 172447, 172647: 4.4 to 44.5 N (1.0 TO 10.0 lbf) I insertion force per peg. or Reference ONLY	

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7.3 **ENVIRONMENTAL REQUIREMENTS**

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
7.3.1	Thermal Shock	Mate connectors: expose for 5 cycles Between temperatures –55 °C and 105 °C; Dwell 0.5 hours at each temperature.	20 milliohms MAXIMUM (change from initial) Visual: No Damage Dielectric Strength per 6.1.3 except 1500VAC test voltage Insulation Resistance per 6.1.2
7.3.2	Thermal Aging	Mate connectors; expose to: 96 hours at 105 ± 2°C	20 milliohms MAXIMUM (change from initial) and Visual: No Damage
7.3.3	Humidity (Steady State)	Mate connectors: expose to a temperature of 60 ± 2°C with a relative humidity of 90-95% for 96 hours. Remove surface moisture and air dry for 1 hour prior to measurements.	20 milliohms MAXIMUM (change from initial) Visual: No Damage Dielectric Strength per 6.1.3 except 1500VAC test voltage Insulation Resistance per 6.1.2
7.3.4	Solderability Dip Test	Per Molex Test Method: SMES-152	Solder area shall have minimum of 95% solder coverage
7.3.5	Wave Solder Resistance	Dip connector terminals tail in solder: Solder Duration: 5 ± 0.5 seconds; Solder Temperature: Use maximum solder temperature from 9.2	Visual: No Damage to insulator housing material
7.3.6	Cold Resistance	Mate connectors: Duration; 96 hours; Temperature: -40 ± 3°C	20 milliohms MAXIMUM (change from initial) and Visual: No Damage
7.3.7	Mixed Flowing Gas	EIA-364-65 with Class IIa Gas concentrations 10 days mated (30µ" Gold plated only)	20 milliohms MAXIMUM (change from initial) and Visual: No Damage
7.3.8	Cyclic Temperature and Humidity	Mate connectors: expose to 24 cycles from 25 °C / 80% RH to 65 °C / 50% RH ramp time: 0.5hr dwell time: 1hr Per EIA-364-1000	20 milliohms MAXIMUM (change from initial) and Visual: No Damage

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8.0 **TEST SEQUENCE GROUPS**

Reliability Test Sequences Based on EIA 364-1000

Group I Temperature Life	Group II Thermal Shock	Group III Vibration	Group IV Mixed Flowing gas (Gold plated only)	Group VII Durability
Initial Contact Resistance EIA-364-23	Initial Contact Resistance EIA-364-23	Initial Contact Resistance EIA-364-23	Initial Contact Resistance EIA-364-23	DWV EIA-364-20
Durability Tin plated: 5 cycles Gold plated: 20 cycles EIA-364-09	Durability Tin plated: 5 cycles Gold plated: 20 cycles EIA-364-09	Durability Tin plated: 5 cycles Gold plated: 20 cycles EIA-364-09	Durability 20 cycles EIA-364-09	Initial Contact Resistance EIA-364-23
Low Level Contact Resistance	Low Level Contact Resistance	Low Level Contact Resistance	Temperature Life (preconditioning)	Durability
Thermal Aging	Thermal Shock	Thermal Aging Pre-condition	Low Level Contact Resistance	Low Level Contact Resistance
Low Level Contact Resistance	Low Level Contact Resistance	Low Level Contact Resistance	Mixed Flowing Gas	DWV EIA-364-20
Reseating 3 cycles	Cyclic Temperature and Humidity EIA-364-31	Random Vibration EIA-364-28 Condition VIID	Low Level Contact Resistance	
Low Level Contact Resistance	Low Level Contact Resistance	Low Level Contact Resistance	Thermal Disturbance	
	Reseating 3 cycles		Low Level Contact Resistance	
	Low Level Contact Resistance		Reseating	
			Low Level Contact Resistance	

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PRODUCT SPECIFICATION

Individual Tests

Terminal
Mating / Unmating Force Per
Circuit

Crimp Terminal Retention Force (In Housing)

Wire Pullout Force (Axial)

Crimp Terminal Insertion Force (Into Housing)

Normal Force

Thumb Latch operation Force

Panel insertion & Withdrawal Forces

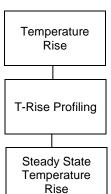
Thumb Latch Yield Strength

Solder PC Tail Header retention Force

Stamped PC Tail Terminal Retention Force into Housing

PCB Engagement Forces

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9.0 SOLDER INFORMATION

These specifications establish standard solderability test methods used to evaluate a products ability to accept molten solder. Solder Process Temperatures and Reflow Solder Profiles will vary based on application, equipment, solder paste, PCB thickness etc.

9.1 SOLDER PROCESS TEMPERATURES

Wave Solder: See Section 9.2 Reflow Solder: Not Rated

Molex Solderability Specification SMES-152

(Click Here)

9.2 MAXIMUM WAVE SOLDER TEMPERATURE

	Plating Type						
Header Type	Matte Tin over Nickel	Bright Tin over Nickel	Tin over Copper				
With Mounting Pegs	240°C	240°C	240°C				
Without Mounting Pegs	260°C	240°C	240°C				
Glow Wire with Pegs Series: 172447 172447 172448 172648	220°C	N/A	N/A				

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10.0 PACKAGING

Parts shall be packaged to protect against damage during normal handling, transit and storage. For specific part packaging details, refer to the packaging specification called out on the applicable product sales drawing. Nylon parts should remain in their original packaging until ready for use to prevent moisture loss or gain. Nylon will absorb moisture which causes dimensions to increase. Excess moisture gain can result in dimensions exceeding specification. See AS-45499-001

11.0 GAGES AND FIXTURES

It is recommended that test plugs (Series 44281) be used for continuity testing of receptacles. Standard mating parts should not be used for harness testing.

NOTE: The use of unauthorized testing devices and/or probes with a Molex product may cause damage to and affect functionality of the Molex product, and such use may void any and all warranties, expressed or implied.

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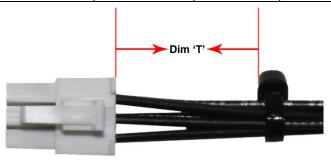


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12.0 CABLE TIE AND/OR WIRE TWIST LOCATION

Circui	t Sizes				
Dual Row	Single Row	Dimension T Minimum			
2-6	2-3	.50" (12.7 mm)			
8	4	.75" (19.1 mm)			
10-12	5-6	1.00" (25.4 mm)			
14-16	7-8	1.25" (31.75 mm)			
18-20	9-10	1.50" (38.09 mm)			
22-24	11-12	1.75" (44.45 mm)			



Note:

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The "T" dimension defines a "free" length of wire, or a length of wire that is not subject to significant bias by external factors such as a wire tie, wire twisting, or other means of bending or deforming of the wires that repositions them from their natural relaxed state or location where they enter the housing. Wires are to be dressed in such a manner to allow the terminals to float freely in the pocket. This dimension is general recommendation and may need to be adjusted for different wire gauges and wire type and insulation thickness and insulation material.

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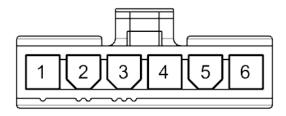


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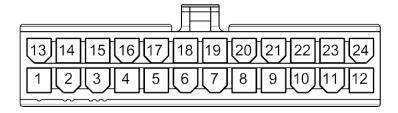


13.0 POLARIZATION AND KEYING OPTIONS

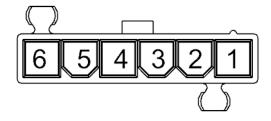
13.1 Single Row Receptacle (Series: <u>46994</u>, <u>5557</u>)



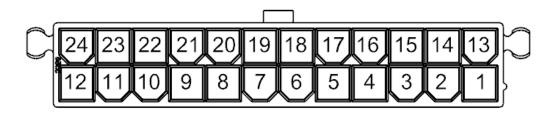
13.2 Dual Row Receptacle (Series: <u>5557</u>, <u>46992</u>)



13.3 Single Row Header / Plug (Series: <u>172647</u>, <u>5566</u>)



13.4 Dual Row Header / Plug (Series: <u>5566</u>, <u>172447</u>)



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